Thermal Characteristics

Package	l _D (continuous) [†]	l _D (pulsed)	Power Dissipation @T _A = 25°C	$I_{ m DR}^{t}$	l _{DRM}	
TO-243AA	100mA	300mA	1.3W [‡]	100mA	300mA	

Notes:

- † I_{D} (continuous) is limited by max rated T_{D}
- # Mounted on FR4 board, 25mm x 25mm x 1.57mm.

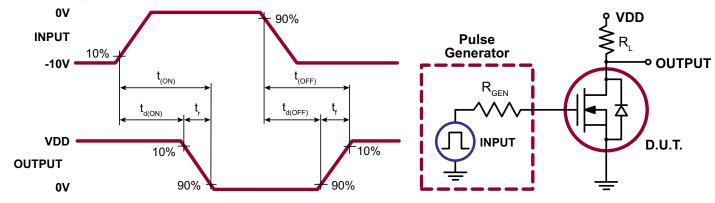
Electrical Characteristics (T_A = 25°C unless otherwise specified)

Sym	Parameter	Min	Тур	Max	Units	Conditions		
BV _{DSX}	Drain-to-source breakdown voltage		-	-	V	$V_{GS} = -5.0V, I_{D} = 100\mu A$		
$V_{GS(OFF)}$	Gate-to-source off voltage	-1.5	-	-3.5	V	$V_{DS} = 15V, I_{D} = 10\mu A$		
$\Delta V_{GS(OFF)}$	Change in V _{GS(OFF)} with temperature	-	-	-4.5	mV/°C	$V_{DS} = 15V, I_{D} = 10\mu A$		
I _{GSS}	Gate body leakage current	-	-	100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$		
		-	_	1.0	μA	V_{DS} = Max rating, V_{GS} = -5.0V		
I _{D(OFF)}	Drain-to-source leakage current	-	-	1.0	mA	$V_{DS} = 0.8$ Max Rating, $V_{GS} = -5.0V$, $T_{A} = 125^{\circ}C$		
I _{DSS}	Saturated drain-to-source current	120	-	-	mA	V _{GS} = 0V, V _{DS} = 15V		
R _{DS(ON)}	Static drain-to-source on-state resistance	-	-	60	Ω	V _{GS} = 0V, I _D = 100mA		
$\Delta R_{DS(ON)}$	Change in R _{DS(ON)} with temperature	-	-	1.1	%/°C	$V_{GS} = 0V, I_D = 100mA$		
G _{FS}	Forward transconductance	140	-	-	mmho	$V_{DS} = 10V, I_{D} = 100mA$		
C _{ISS}	Input capacitance	-	-	120		$V_{GS} = -5.0V,$ $V_{DS} = 25V,$ f = 1.0MHz		
C _{oss}	Common source output capacitance	-	-	15	pF			
C _{RSS}	Reverse transfer capacitance	-	-	10				
t _{d(ON)}	Turn-on delay time	-	-	10				
t _r	Rise time	-	-	15	no	$V_{DD} = 25V,$ $I_{D} = 100 \text{mA},$ $R_{GEN} = 25\Omega,$		
t _{d(OFF)}	Turn-off delay time	-	_	20	ns			
t _f	Fall time	-	-	35		GEN ,		
V _{SD}	Diode forward voltage drop	-	-	1.8	V	V _{GS} = -5.0V, I _{SD} = 100mA		
t _{rr}	Reverse recovery time	-	800	-	ns	$V_{GS} = -5.0V, I_{SD} = 100mA$		

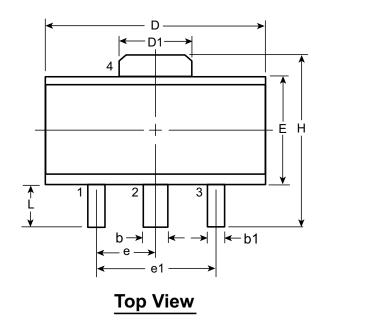
Notes:

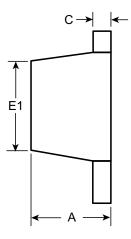
- 1. All D.C. parameters 100% tested at 25°C unless otherwise stated. (Pulse test: 300µs pulse, 2% duty cycle.)
- 2. All A.C. parameters sample tested.

Switching Waveforms and Test Circuit



3-Lead TO-243AA (SOT-89) Package Outline (N8)





Side View

	Symbo	ol	Α	b	b1	С	D	D1	Е	E1	е	e1	Н	L	ı
		MIN	1.40	0.44	0.36	0.35	4.40	1.62	2.29	2.00 [†]			3.94	0.73 [†]	
Dimensions (mm)	NOM	-	-	-	-	-	-	-	-	1.50 BSC	3.00 BSC	-	-		
	MAX	1.60	0.56	0.48	0.44	4.60	1.83	2.60	2.29			4.25	1.20		

JEDEC Registration TO-243, Variation AA, Issue C, July 1986.

† This dimension differs from the JEDEC drawing

Drawings not to scale.

Supertex Doc. #: DSPD-3TO243AAN8, Version F111010.

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to http://www.supertex.com/packaging.html.)

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